



Status of MRPC TOF technology

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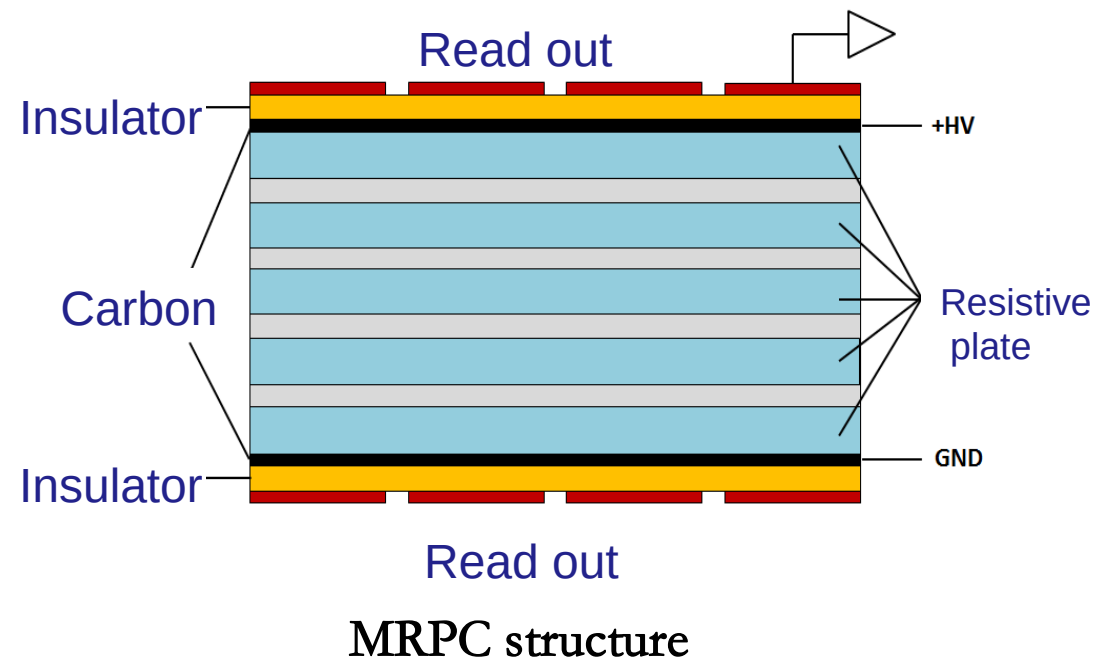


Abstract:

- Introduction of MRPC
- Introduction of three generation MRPC TOF
- Status of TOF of STAR, CBM and SoLID
- Conclusion



MRPC introduction



Standard parameters:

Resistivity of glass: $\sim 10^{12} \Omega \cdot \text{cm}$

Working gas:

90% Freon + 5% iso-butane + 5% SF₆

Time resolution <100ps

Efficiency >95%

Charge: a few PC

Dark current: a few nA

Noise $\sim 1 \text{ Hz/cm}^2$

Rate <100 Hz/cm²

Large area, low cost

MRPC application:

1. Application in nuclear physics experiments
2. Application in industry (Muon tomography)
3. Application in medicine (TOF-PET)



How to increase rate of MRPC

The voltage drop in the gas gap:

$$\bar{V}_{drop} = V_{ap} - \bar{V}_{gap} = \bar{I}R = \bar{q}\phi\rho d$$

The smaller the voltage drop, the higher efficiency and higher rate capability!

Two main ways to improve rate capability:

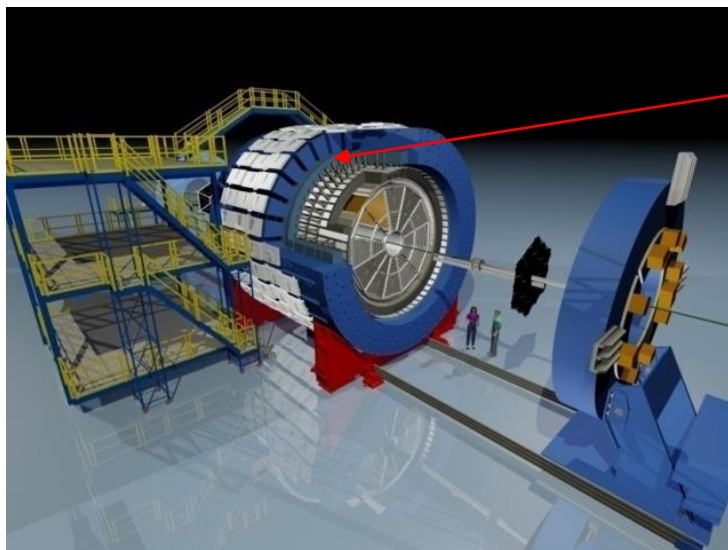
- Reducing bulky resistivity of electrode glass (CBM)
- Reducing the avalanche charge (ATLAS)

Other methods:

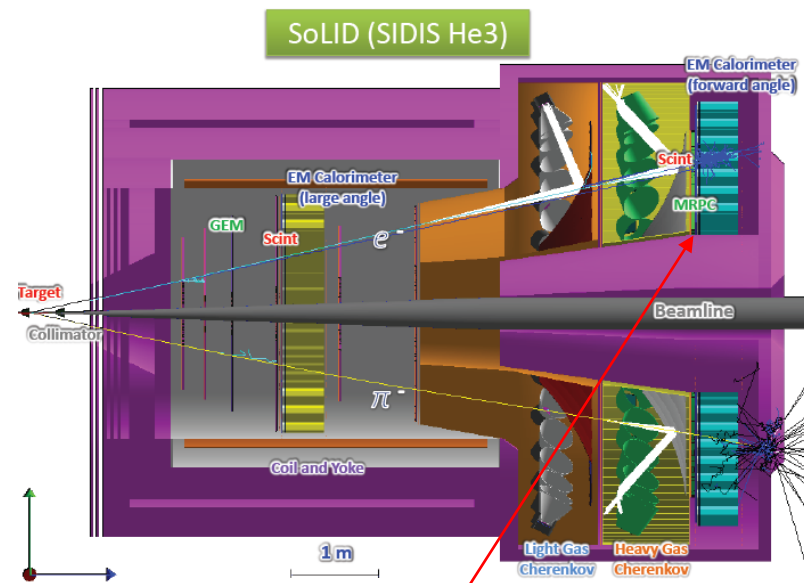
- Reducing the thickness of glass
- Warming the detector



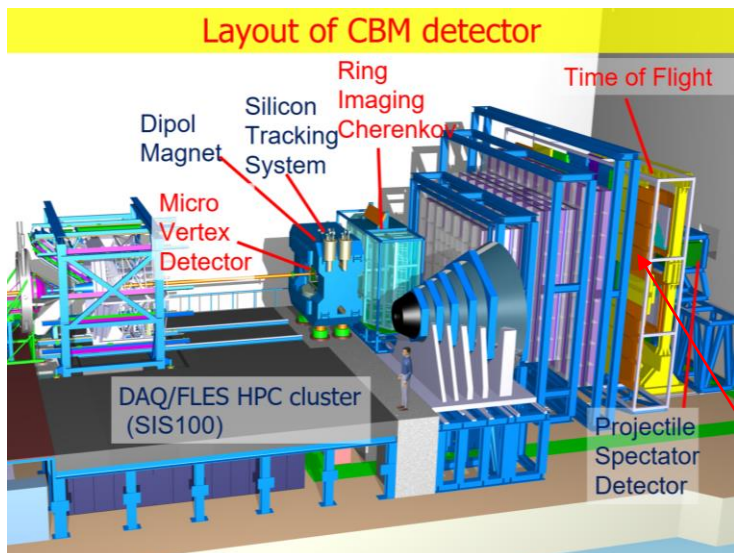
Typical MRPC TOF



RHIC-STAR TOF
Float glass



JLab-SoLID TOF
High rate and 20ps resolution



FAIR-CBM TOF
High rate- low resistive glass



Key technology

1st generation TOF:

Requirement: Time resolution: $<80\text{ps}$

Rate : $<1\text{kHz/cm}^2$

Technology: common glass MRPC+NINOs +HPTDC

Analysis method: TOT slewing correction

2st generation TOF:

Requirement: Time resolution: $<80\text{ps}$

Rate : 30kHz/cm^2

Technology: low resistive glass MRPC+PADI +GET4

Analysis method: TOT slewing correction

3st generation TOF:

Requirement: Time resolution: $<20\text{ps}$

Rate : 20kHz/cm^2

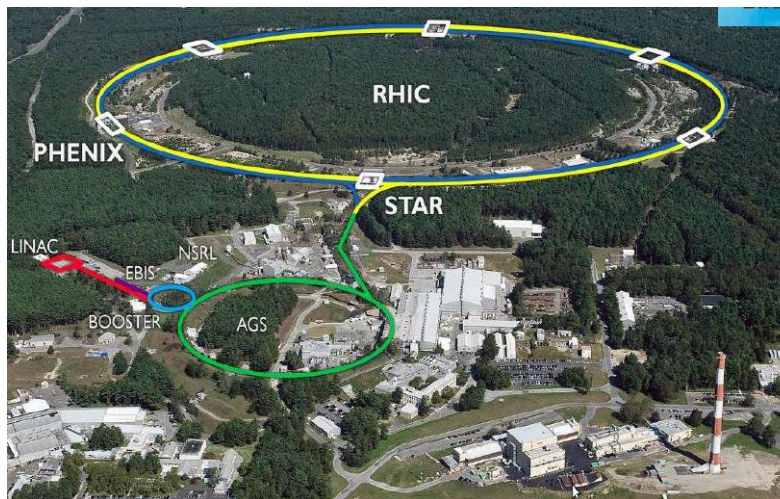
Technology: low resistive glass MRPC+SCA +ADC

Analysis method: TOT slewing correction

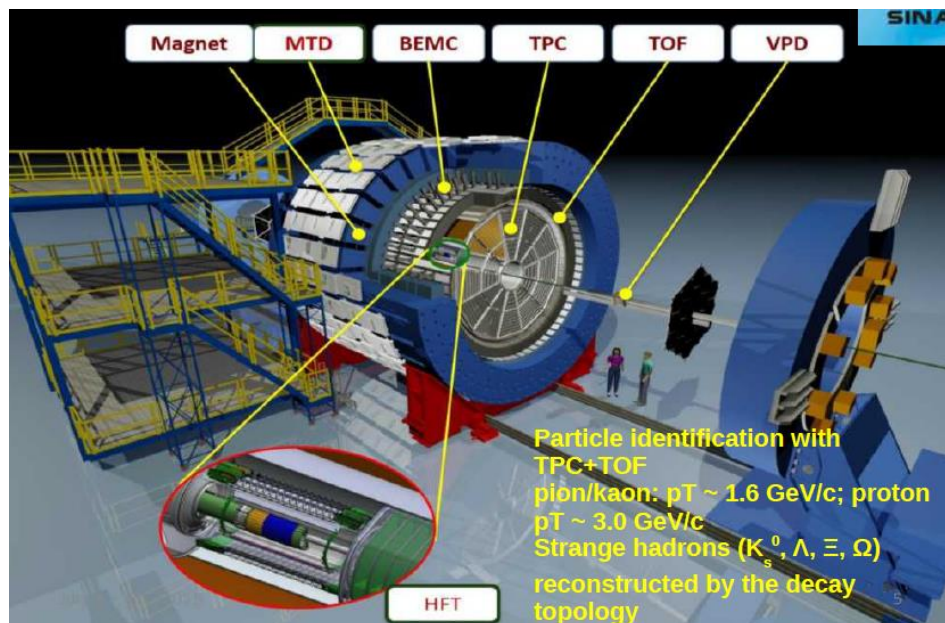
Deep learning+ Neural network



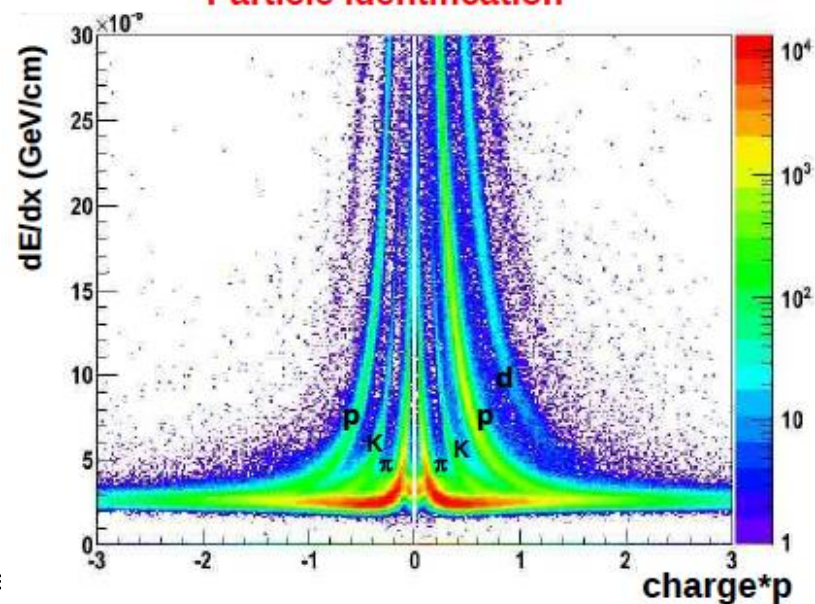
RHIC-STAR



Collision species	C.M. Energy per nucleon pair (GeV)	Physics
Polarized p+p	510, 200, 150	Spin physics
Au+Au	200, 130, 62.4, 39, 27, 19.6, 14.5, 11, 7.7	Quark Gluon Plasma properties, QCD Critical point search
Cu+Cu, Cu+Au	200, 62.4, 19.6, 22.4	Study initial conditions
d+Au	200	Cold nuclear matter
U+U	193	Study initial conditions

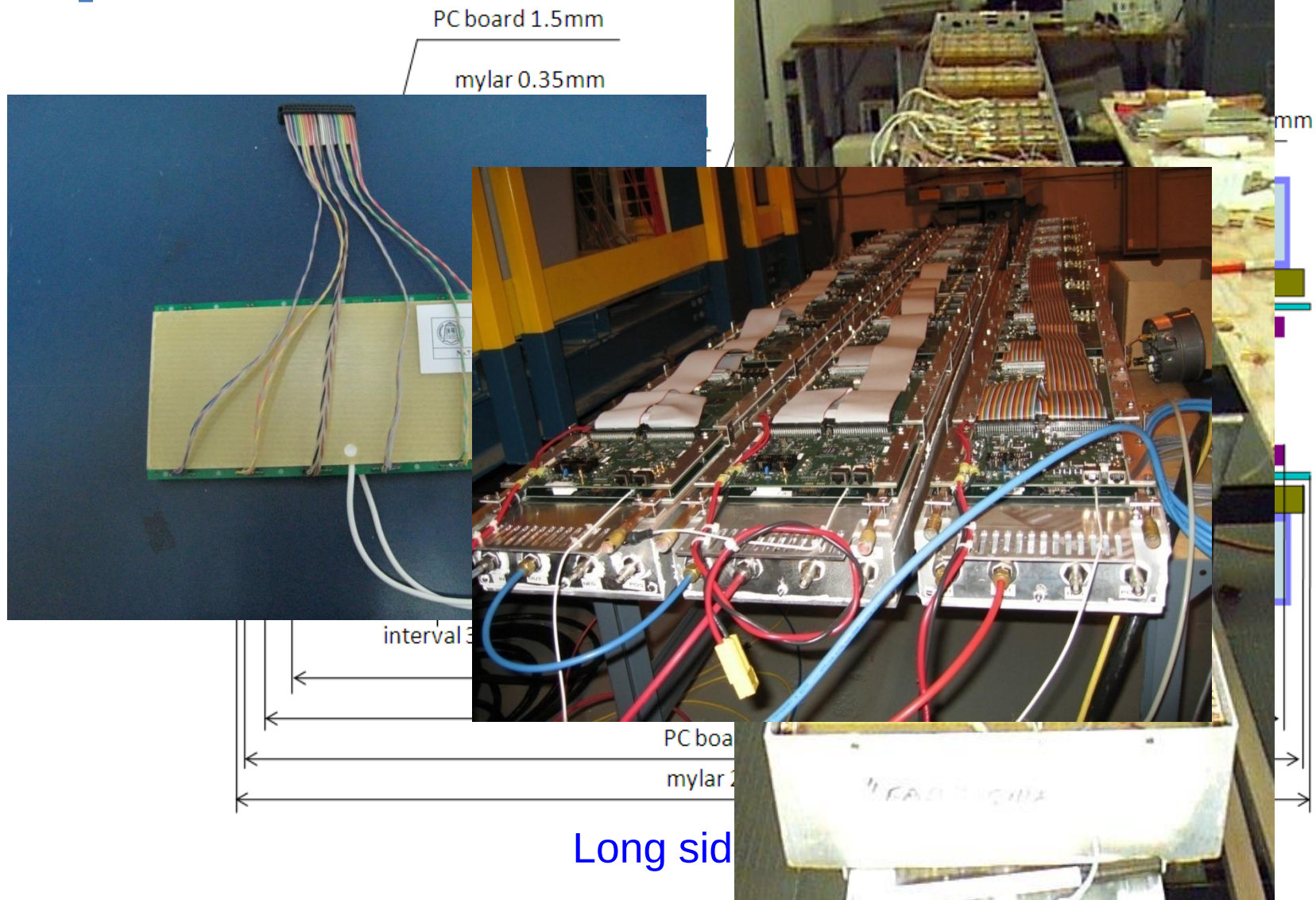


Particle identification



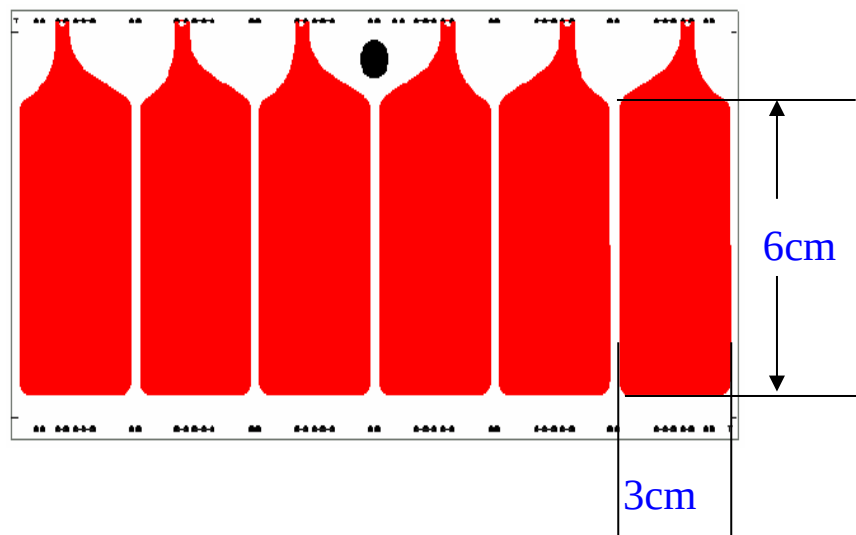


STAR-TOF MRPC



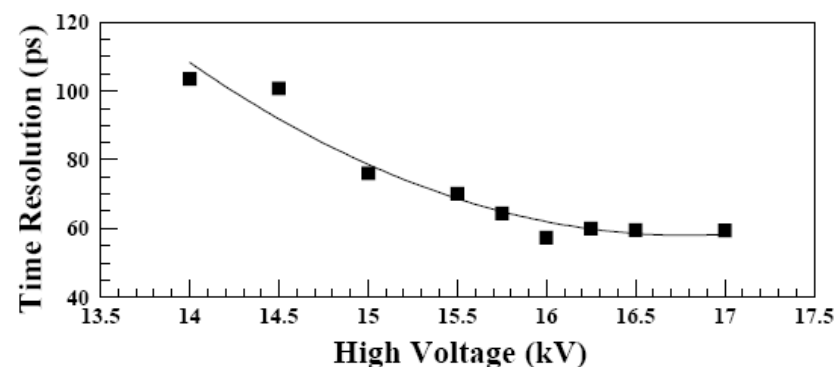
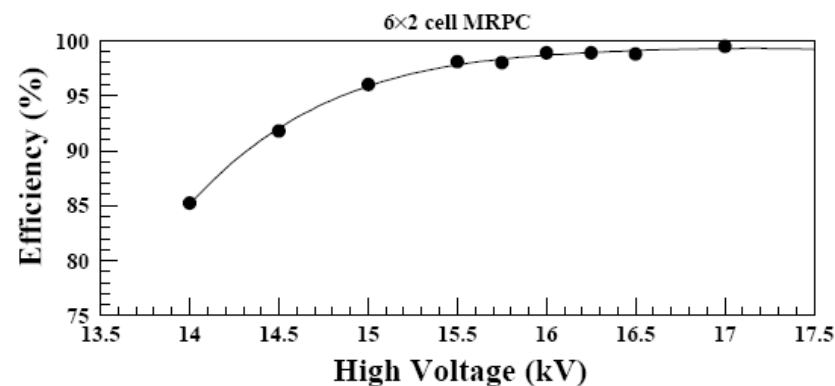


STAR MRPC performance



Readout pad

Glass: $\sim 4 \times 10^{12} \Omega \cdot \text{cm}$
Carbon tape: $500 \text{ k} \Omega / \square$
Gas gap: $6 \times 0.22 \text{ mm}$
Working gas: 95% F134a+5% iso-butane
Time resolution: 70ps
Efficiency >90%
Rates capability: $< 500 \text{ Hz/cm}^2$!





MRPC mass production



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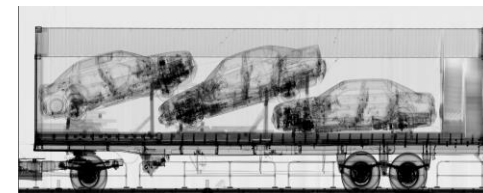
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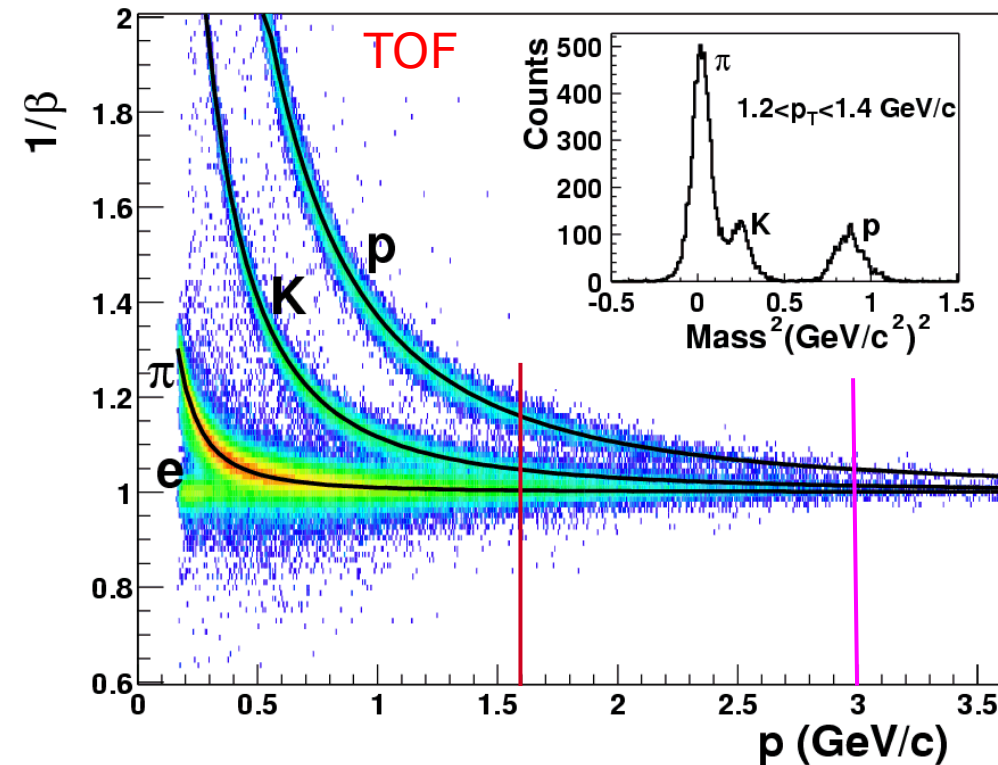
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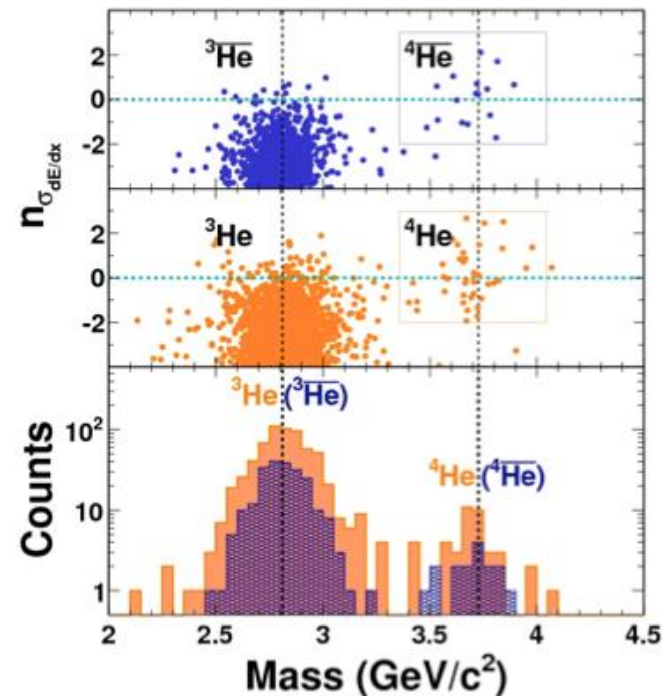
PID of STAR-TOF



TOF PID:

$\pi / k \sim 1.6 \text{ GeV}/c$,

$(\pi, k)/p \sim 3.0 \text{ GeV}/c$



Observation of the antimatter helium-4 nucleus

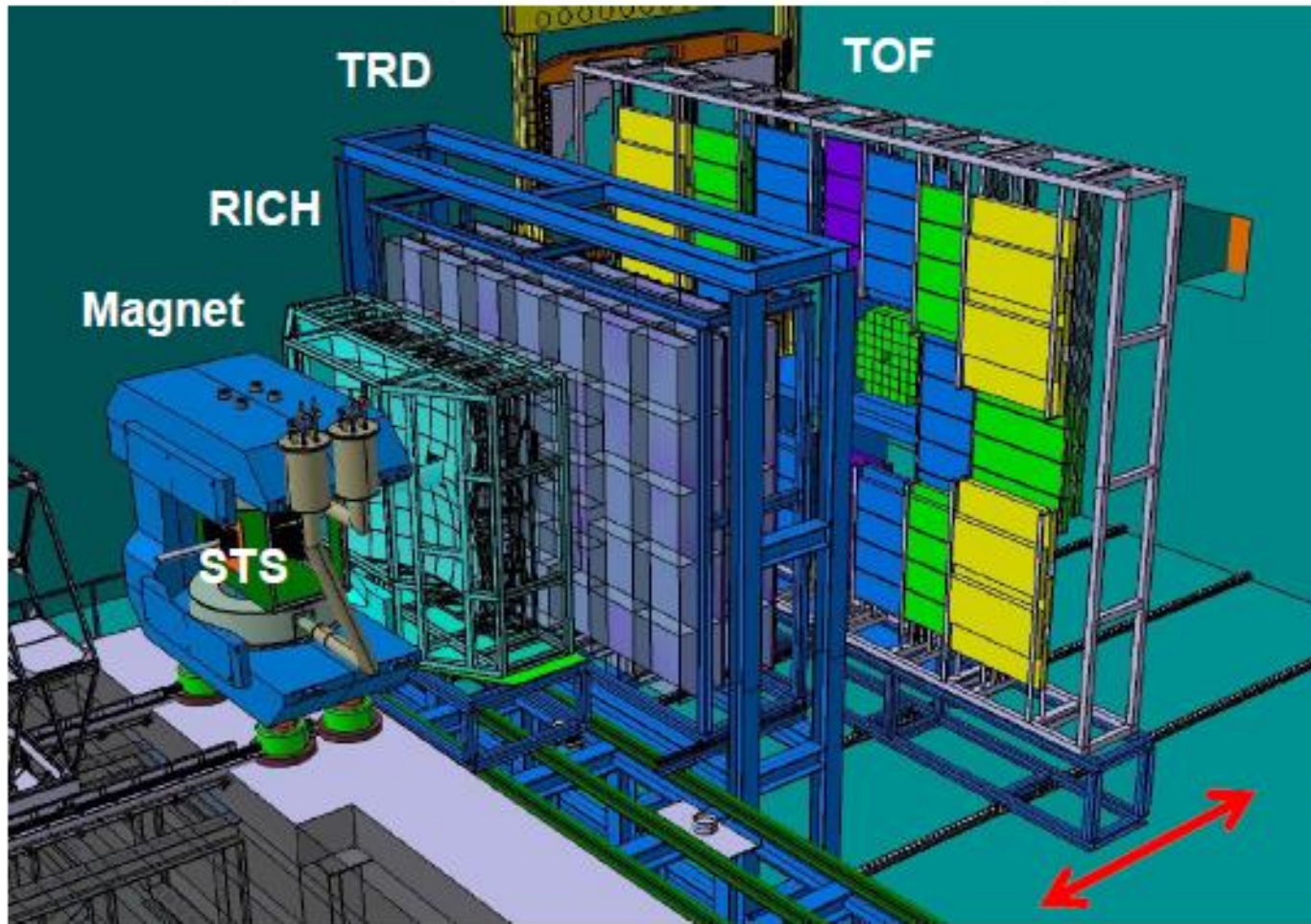
The STAR Collaboration*

Nature 473 (2011) 353



Layout of CBM detector

Engineering design of the CBM experiment



Nominal ToF position is between 6 m and 10 m from the target

Movable design allows for optimization of the detection efficiency of weakly decaying particles (Kaons)

Interaction rate 10 MHz

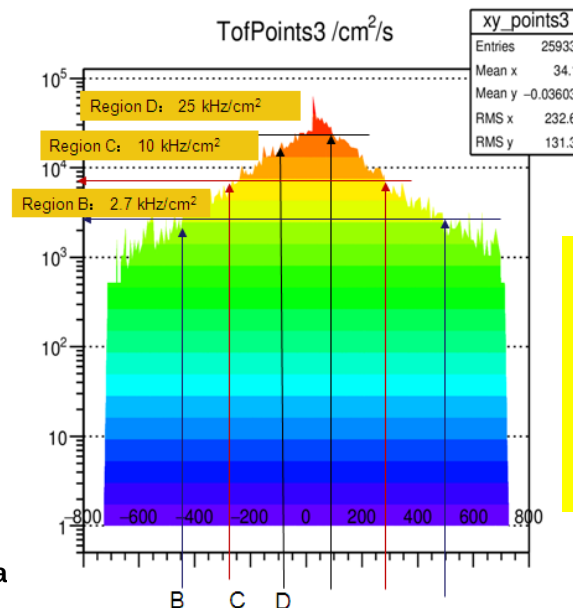


The structure of CBM-TOF wall



CBM-ToF Requirements

- Full system time resolution $\sigma_T \sim 80$ ps
- Efficiency $> 95\%$
- Rate capability ≤ 30 kHz/cm²
- Polar angular range $2.5^\circ - 25^\circ$
- Occupancy $< 5\%$
- Low power electronics
(~100.000 channels)
- Free streaming data acquisition



Au+Au, Center,
10AGeV
Simulated with
CBM ROOT



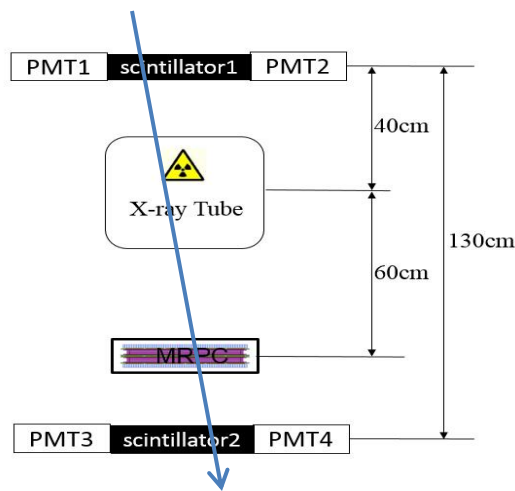
Development of low resistive glass

Performance of the glass

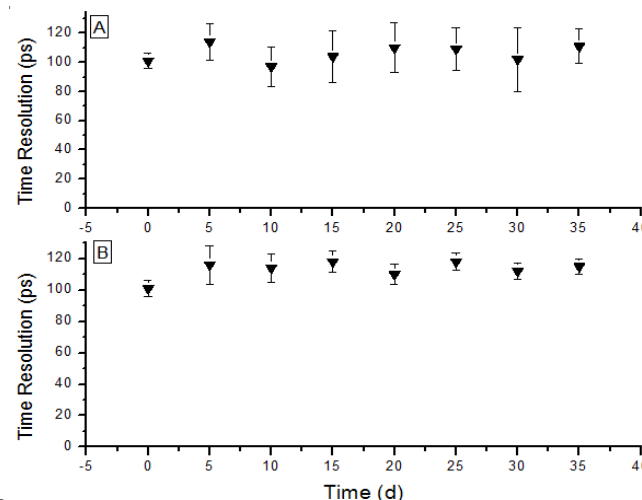
Maximal dimension	32cm × 30cm
Bulk resistivity	$10^{10} \Omega\text{cm}$
Standard thickness	0.7, 1.1mm
Thickness uniformity	20 μm
Surface roughness	< 10nm
Dielectric constant	7.5 - 9.5
DC measurement	Ohmic behavior stable up to 1 C/cm ²



Glass mass production
Yield >100m²/month



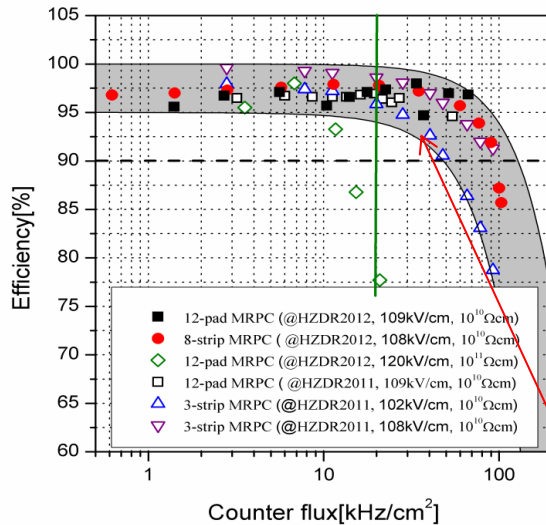
Aging test with X-ray source



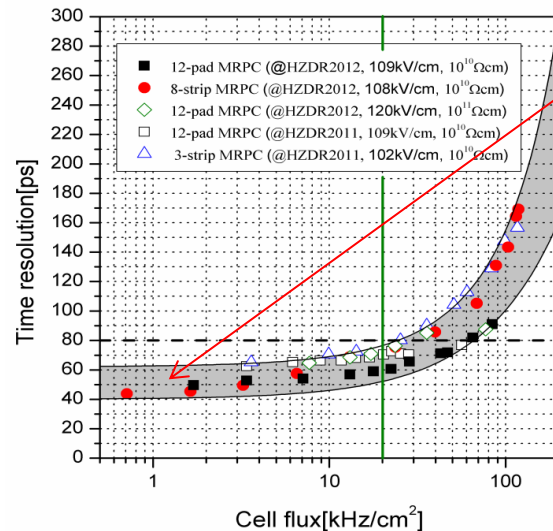
Online test system. The efficiency and time resolution can be obtained by cosmic ray while irradiated by X-rays. 0.1C/cm² charge is accumulated in 35 days.



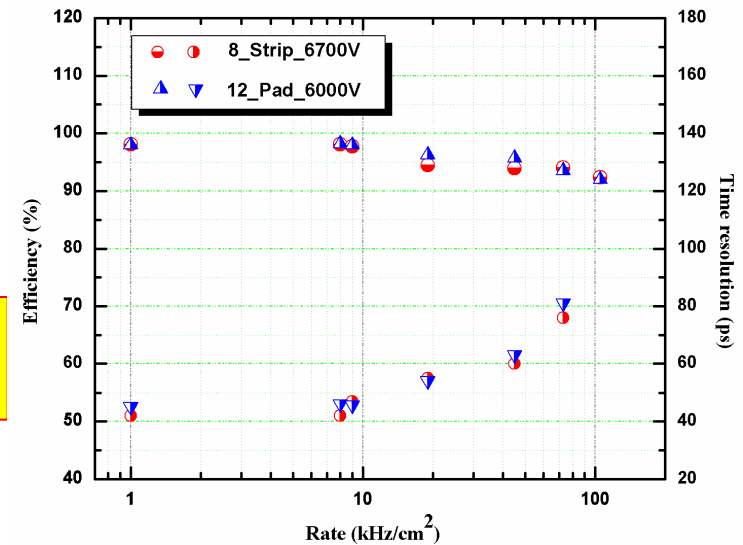
Rate capability of high rate MRPC



Rate: 70kHz/cm²
Time resolution: 40 ps



Test results at Nuclotron, Dubna, 2013



Even though the rate is **70kHz/cm²**, the efficiency is still higher than **90%** and the time resolution is about **80ps**.



Design of strip-MRPC for high rate region

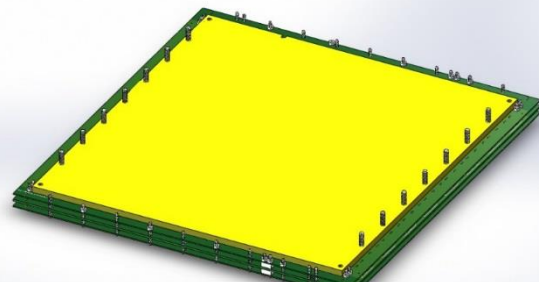
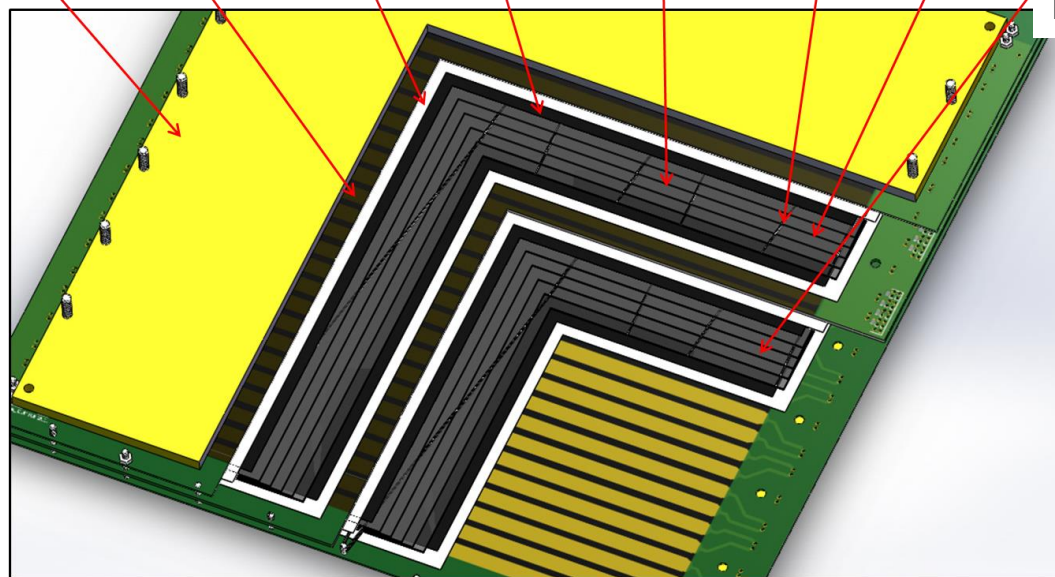
Glass: low resistive glass

0.7mm thick, 33cm x 27.6cm

Strip: 27cm x 0.7cm, 0.3cm interval, 32 strips

Gas gap: 8 x 0.25mm, two stacks

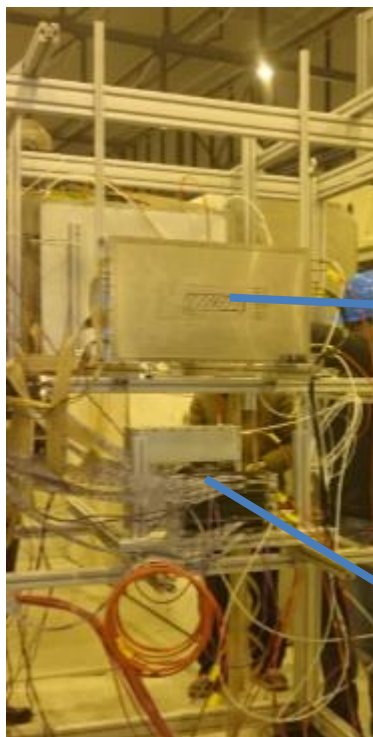
Honey PCB Mylar Graphite Glass Fish line Upper stack lower stack





Beam test @ SPS Feb 2015

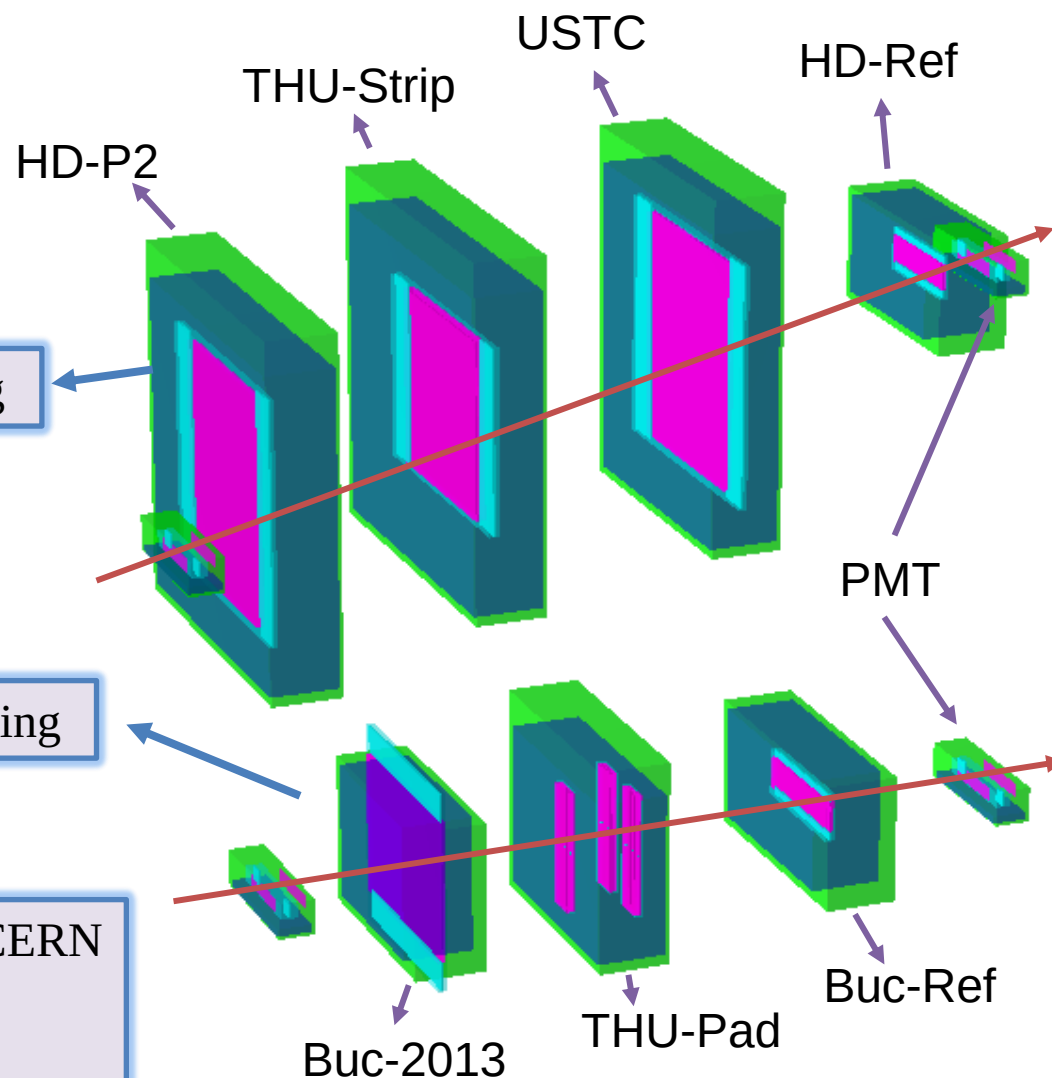
Experimental Setup:



Up setting

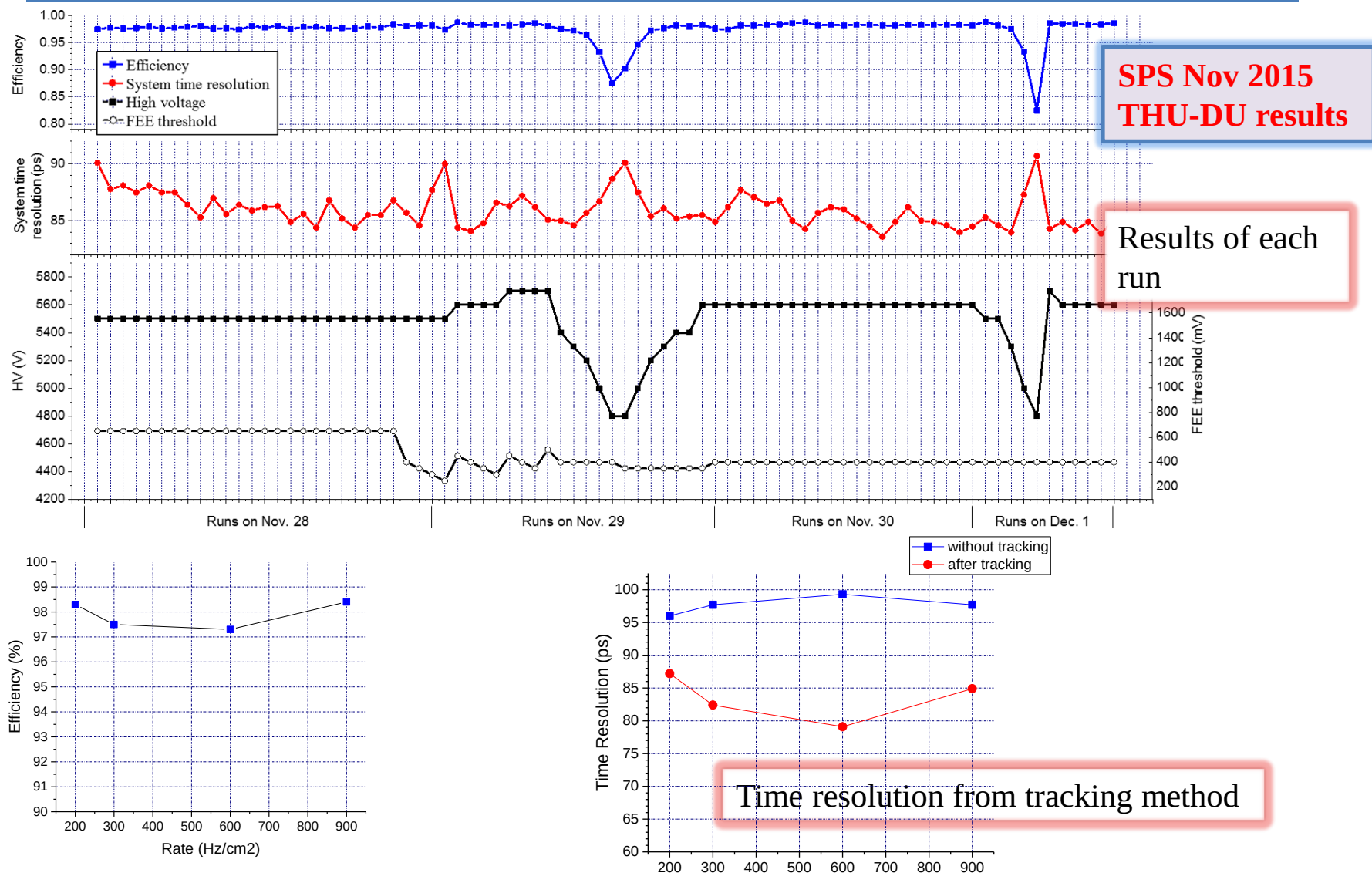
Down setting

High rate test in February 2015 at SPS CERN
13 GeV Ar beam
Flux rate **around 1kHz/cm²**





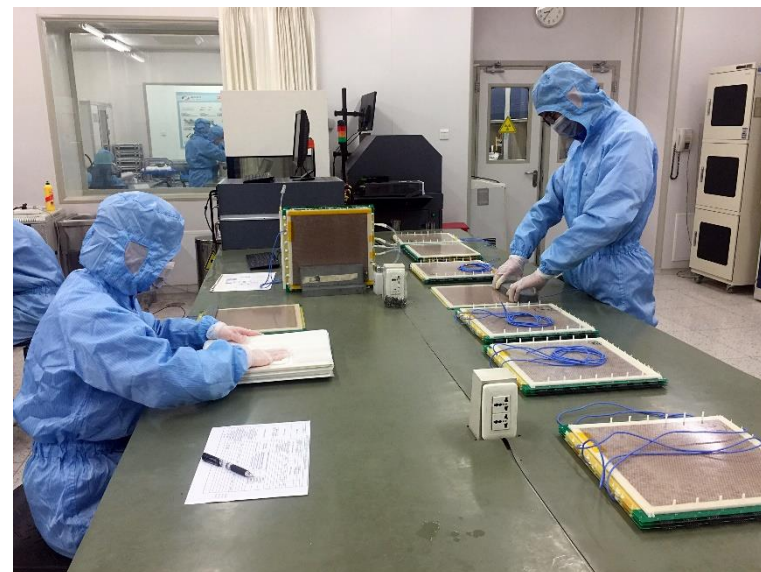
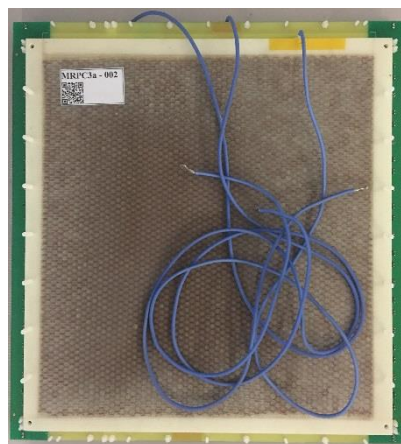
Performance of the prototype



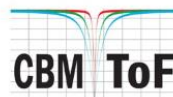


Mass production of high rate MRPC

Two-dimensional code of MRPC



Development of MRPC
for CBM-ToF



Introduction
Material
Module Test
Other Stuff

List of Tsinghua MRPC modules #001 - #040

#001	#002	#003	#004	#005
#006	#007	#008	#009	#010
#011	#012	#013	#014	#015
#016	#017	#018	#019	#020
#021	#022	#023	#024	#025
#026	#027	#028	#029	#030

Production website:

http://hepd.ep.tsinghua.edu.cn/CBM_TOF/

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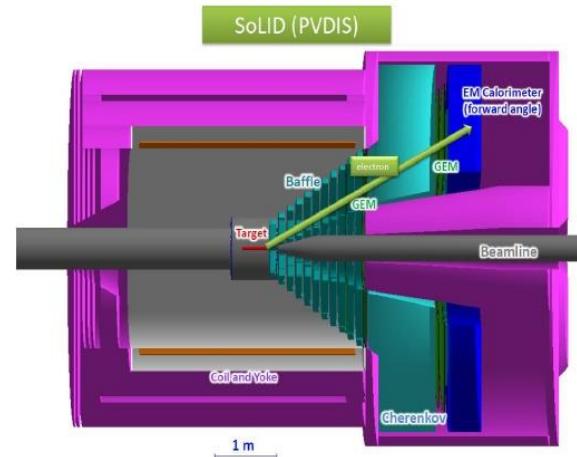
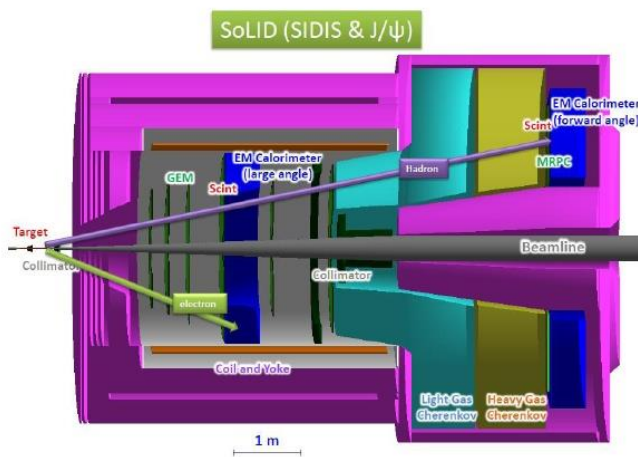
MRPC生产记录表 / MRPC3a Quality Assurance Table									
MRPC ID	MRPC3a - 005								
玻璃 / Glass	来自编号与批次 / Glass Batch No.	NO.9 151225		用料数量/Amount		6			
	来自编号与批次 / Glass Batch No.	NO.11 151225		用料数量/Amount		4			
	来自编号与批次 / Glass Batch No.			用料数量/Amount					
	来自编号与批次 / Glass Batch No.			用料数量/Amount					
	来自编号与批次 / Glass Batch No.			用料数量/Amount					
电极玻璃 / Electrode	面电阻 / Surface Resistance (M2/sq)	Point 1	Point 2	Point 3	Point 4	Point 5			
	电极玻璃1 / Electrode 1	8	2	3	7	7			
	电极玻璃2 / Electrode 2	3	3	4	3	3			
	电极玻璃3 / Electrode 3	5	8	5	8	5			
	电极玻璃4 / Electrode 4	8	4	3	5	5			
蜂窝板 / Honeycomb	✓								
PCB上下板 / Top & Bottom PCB	✓								
PCB中间板 / Middle PCB	焊接保护电阻 / Protection Resistor	外圈=电阻号与地之间电阻是否均为100kΩ / Resistance Measured on Outside Resistor			✓	问题数量 / Unqualified		0	
		内圈=电阻号与地之间电阻是否均为200kΩ / Resistance Measured on Inside Resistor			✓	问题数量 / Unqualified		0	
	焊接双排插针 / Connector	16个插座与电路板的厚度是否均<6.7mm / Thickness of the connectors			✓	问题数量 / Unqualified		0	
Mylar膜 / Mylar	✓								
PCB上下板高压 / Top & Bottom HV	✓								
PCB中间板高压 / Middle HV	✓								
鱼鳞 / Spacer	✓								
厚度 / Thickness	Point 1	Point 2	Point 3	Point 4	Point 5	Point 6	Point 7	Point 8	
上下PCB / Between Top & Bottom PCB	11.44	11.47	11.44	11.41	11.57	11.45	11.59	11.52	
上中PCB / Between Top & Middle PCB	4.61	4.77	4.67	4.76	4.66	4.79	4.72	4.77	
下中PCB / Between Bottom & Middle PCB	4.63	5.03	5.02	4.87	4.96	4.84	4.84	4.74	
总厚度 / Total Thickness	25.98	25.92	26.11	26.12	26.03	26.13	26.15	26.05	
继续人员签字 / Signature	杨洋林								
日期 / Date	08/09/2017								
备注 / Note									



Overview of SoLID

Solenoidal Large Intensity Device

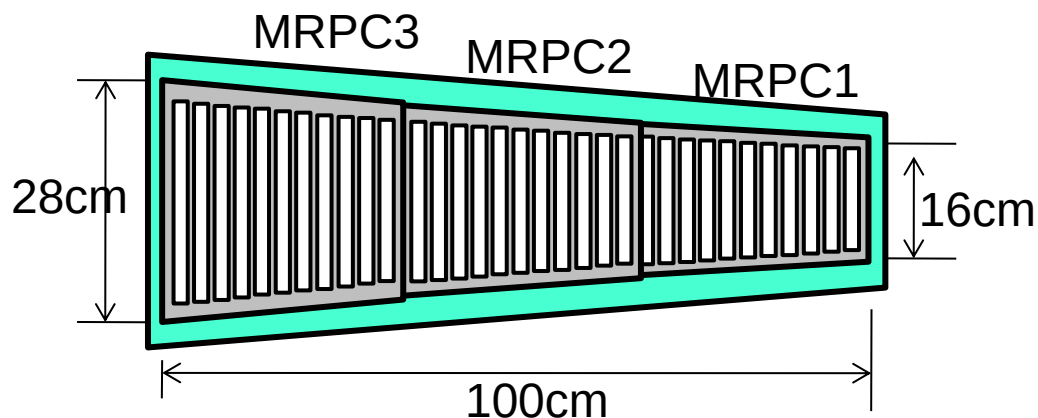
- Full exploitation of JLab 12 GeV Upgrade
 - A Large Acceptance Detector AND Can Handle High Luminosity (10^{37} - 10^{39})
 - Take advantage of latest development in detectors, data acquisitions and simulations
 - Reach ultimate precision for SIDIS (TMDs), PVDIS in high-x region and threshold J/ψ
- 5 highly rated experiments approved (+3)
 - Three SIDIS experiments, one PVDIS, one J/ψ production (+ three run group experiments)
- Strong collaboration (250+ collaborators from 70+ institutes, 13 countries)
 - Significant international contributions (Chinese collaboration)



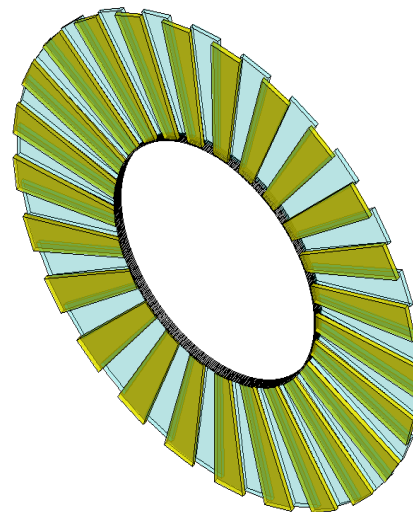
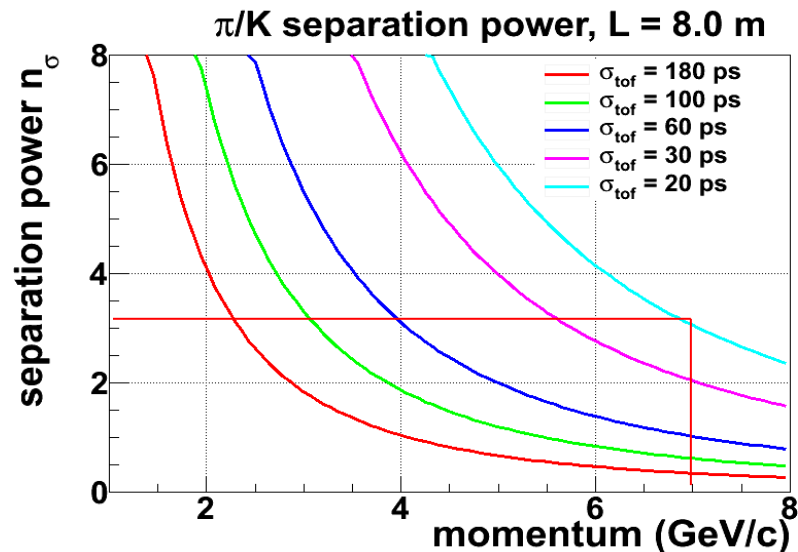


SoLID-TOF structure

- The MRPC is developed for the TOF of SoLID
- Main Requirements for TOF:
 - π/k separation up to 7GeV/c
 - Time resolution < 20ps
 - Rate capability > 20kHz/cm²



SoLID-TOF super module

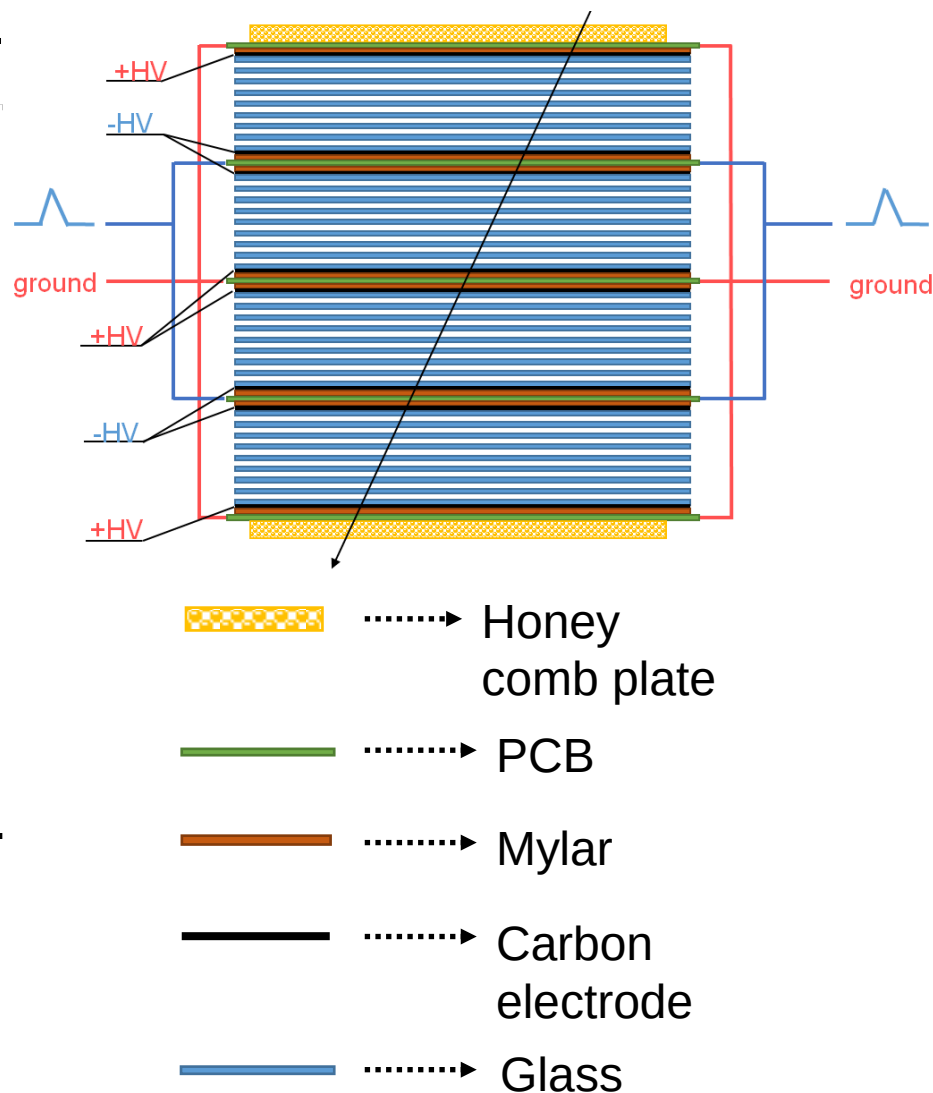


SoLID-TOF structure



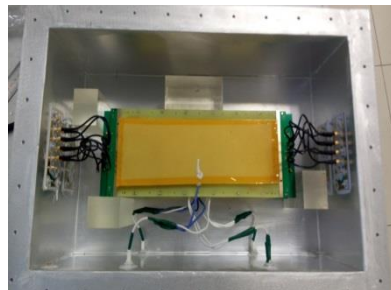
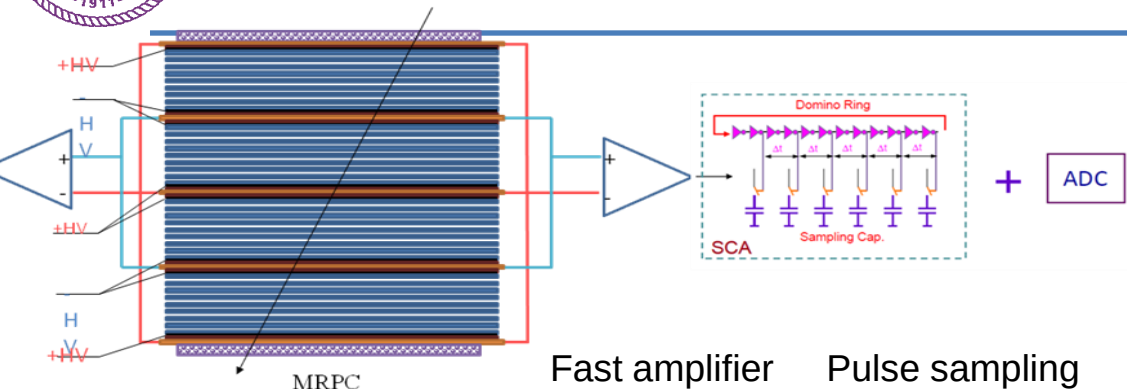
Design of 3^g MRPC for SoLID

Item	dimension/mm
Honeycomb	$90 \times 265 \times 7.5$
Outer PCB	$120 \times 298 \times 0.6$
Middle PCB1	$120 \times 298 \times 1.2$
Middle PCB2	$120 \times 328 \times 1.2$
Strip length	268
Strip width	7
Mylar	$90 \times 268 \times 0.25$
Glass	$80 \times 258 \times 0.5$
Carbon	72×250
Gas gap width	0.104
Number of gas gap	32

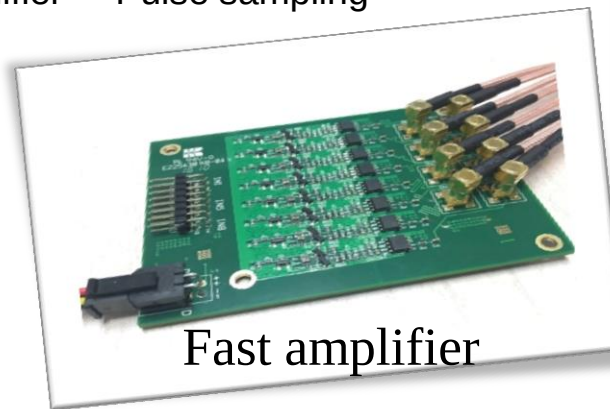




Readout chain



Gas box



Fast amplifier



Fast amplifier

DT5742

Waveform
Digitizer
DT5742



- DRS4-V5 chip
- 16 channels
- 12bit 5GS/s
- ~ 8 points for leading edge of MRPC



Typical wave form sampling chip

Chip	Sampling Frequency (GHz)	Bandwidth GHz	Number of samples	Number of channels	Readout frequency (MHz)	Resolution (ps)
PSEC4	4 to 15	1.5	256	6	40 to 60	9
SAMPIC	3 to 8.2	1.6	64	16 – 8 (at 10 GHz)	80	5
DRS4	0.7 to 5 GHz	0.950	1024	9	33	1
DRS5	10	3	4096	32	300	5
PSEC5	5 to 15	1.5 to 2	32768	4	500	5



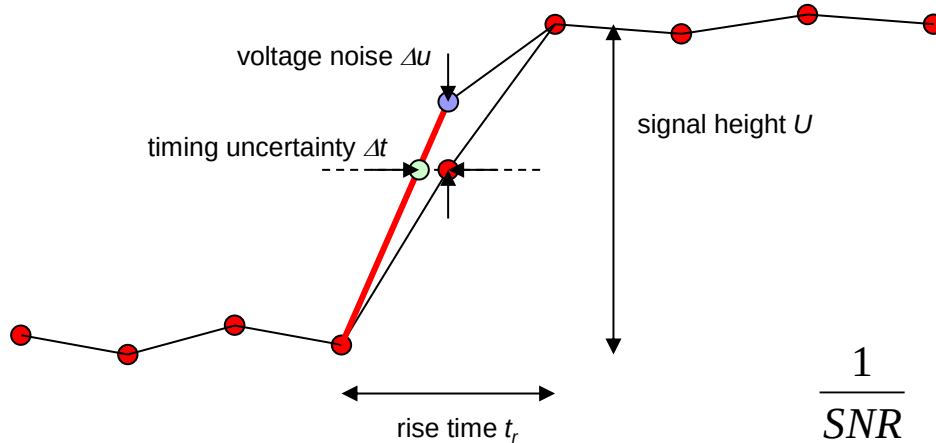
Deep learning and Neural network

- **Artificial neural networks(NN) are powerful tools for solving complex pattern recognition problems characterized by significant non–linearity**
- **Widely used in high energy physics**
- **For example, several sets of NN are used in the tracking reconstruction in ATLAS experiment**
- **Introduce NN to MRPC ?**
- **Training the NN with simulation data, and test with experiment data**



Comparison

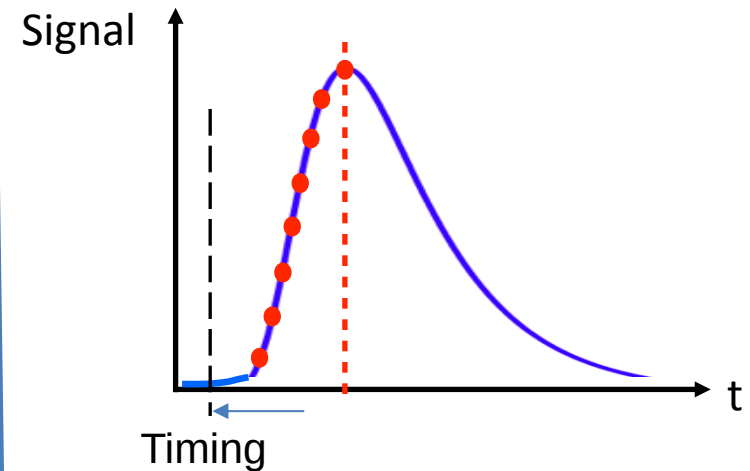
Threshold method



$$\Delta t = \frac{\Delta u}{U} \cdot t_r = \frac{\Delta u}{U \sqrt{n}} \cdot t_r = \frac{\Delta u}{U} \cdot \frac{t_r}{\sqrt{t_r \cdot f_s}} = \frac{\Delta u}{U} \cdot \frac{\sqrt{t_r}}{\sqrt{f_s}}$$

number of samples on slope

Neural network

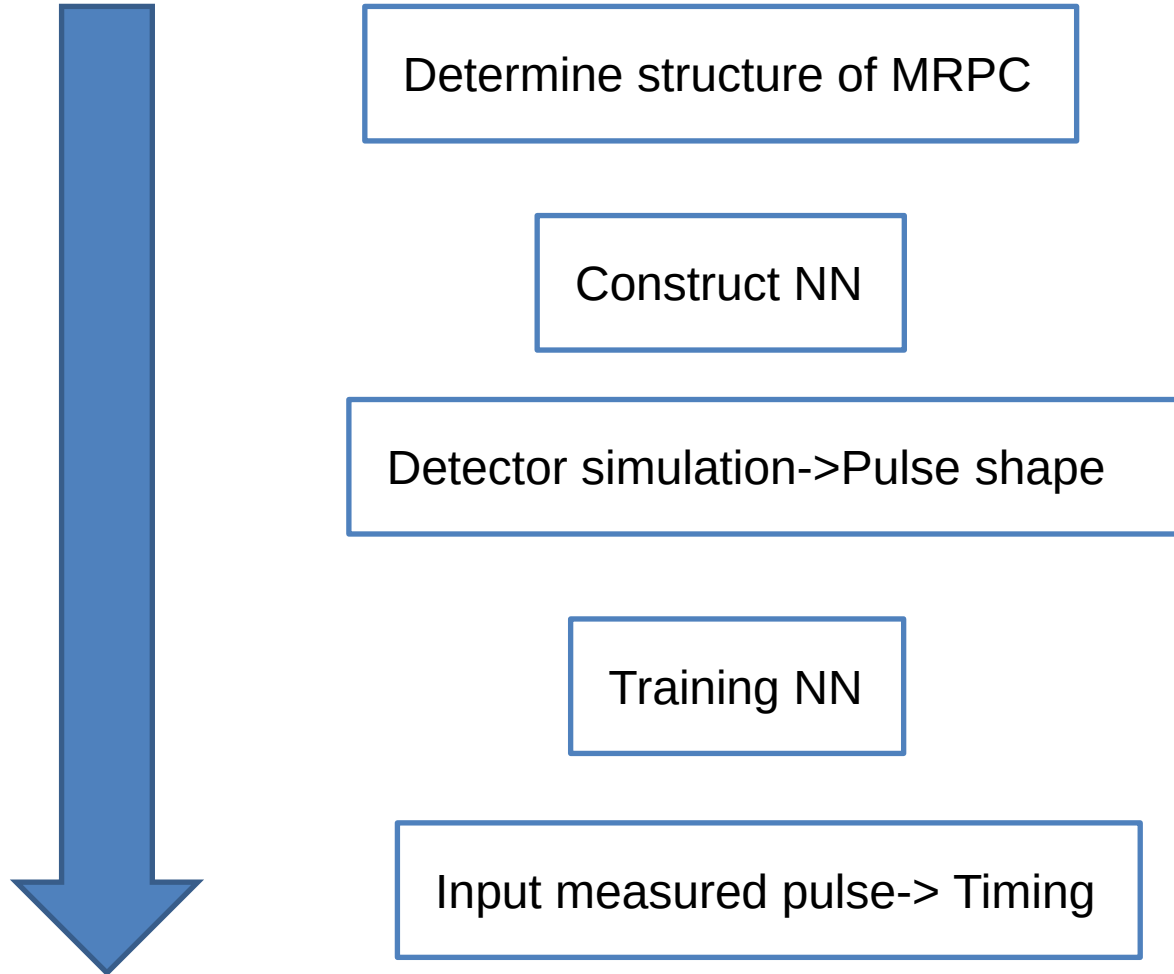


From leading edge → Particle incident time

- Avalanche progress
- Charge induce
- Shaped by electronics



Neural network analysis method



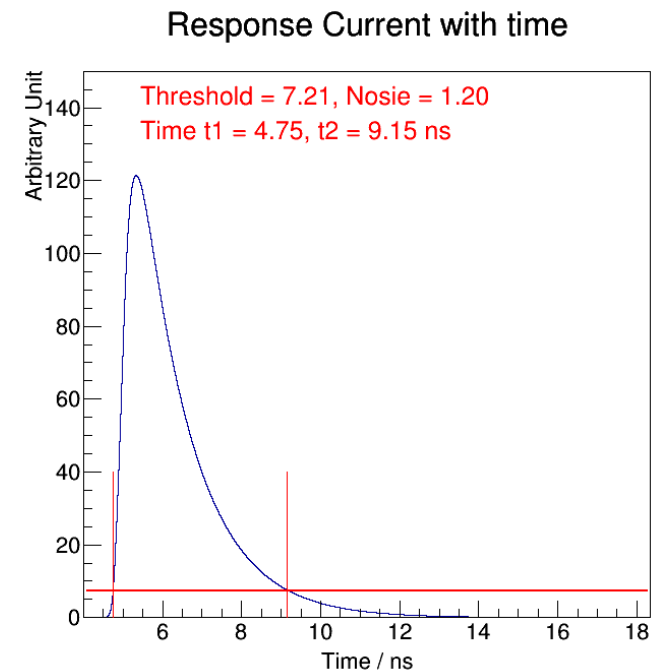


MRPC simulation

- Physics model——**primary ionization**:
- Photo Absorption Ionization(**PAI**) model
- Induced charge signal
- Shaped by electronics
- Train neural network

See Fuyue's poster:

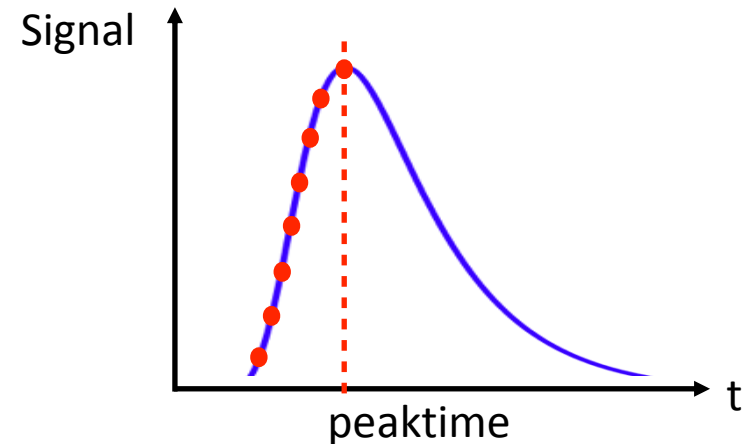
A neural network based algorithm for MRPC time reconstruction





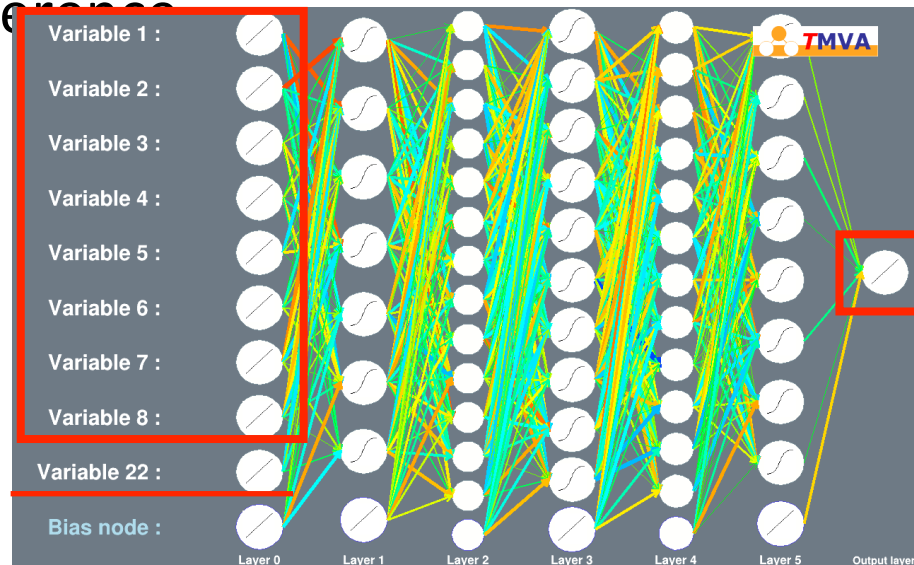
Analysis with neural network

- Feed the waveform into a fully connected neural network
- 5 hidden layers
- 8 points along the leading edge
- Peaktime as a time reference
- TMVA package



Waveform

Peaktime

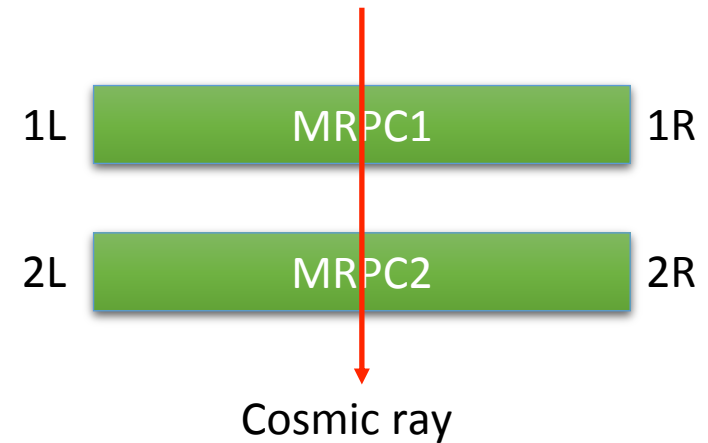
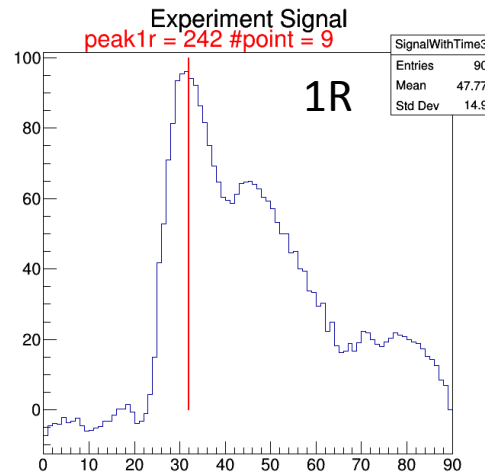
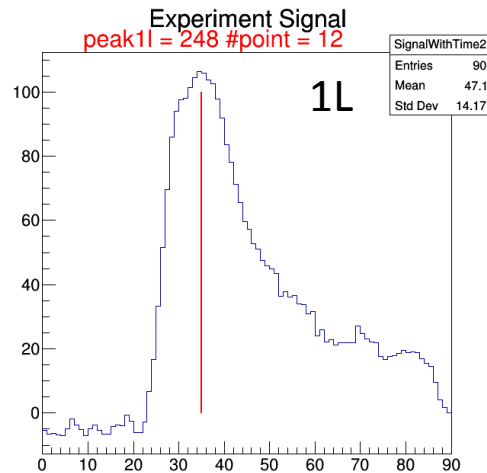


Particle
arrived
time



Analysis with neural network

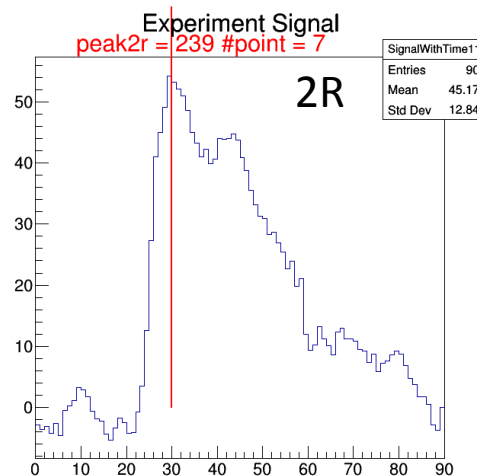
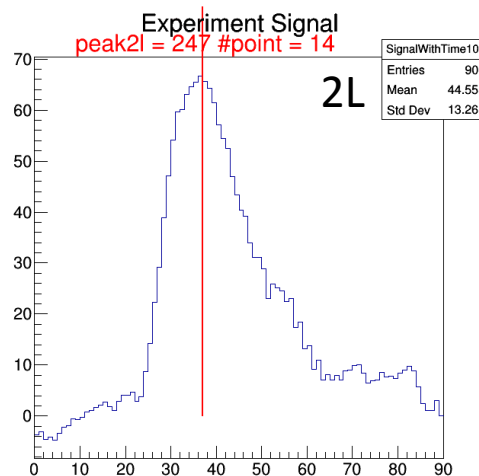
- **Test** the model with the experiment data and get the estimated time



For 1L,1R,2L,2R, we will get

$$t_{est1} = \frac{t_{estimated1L} + t_{estimated1R}}{2}$$

$$t_{est2} = \frac{t_{estimated2L} + t_{estimated2R}}{2}$$





Analysis with neural network

- Test system: 2 MRPC

$$\begin{aligned}\sigma(\Delta t) &= \sigma(t_{res1} - t_{res2}) = \sqrt{\sigma^2(t_{resi1}) + \sigma^2(t_{resi2})} = \sqrt{2\sigma_{MRPC}^2} \\ &= \sigma(t_{true2} - t_{est2} - t_{true1} + t_{est1}) = \sigma(t_{est1} - t_{est2}) \\ &= \sigma\left(\frac{t_{est1l} + t_{est1r}}{2} - \frac{t_{est2l} + t_{est2r}}{2}\right)\end{aligned}$$

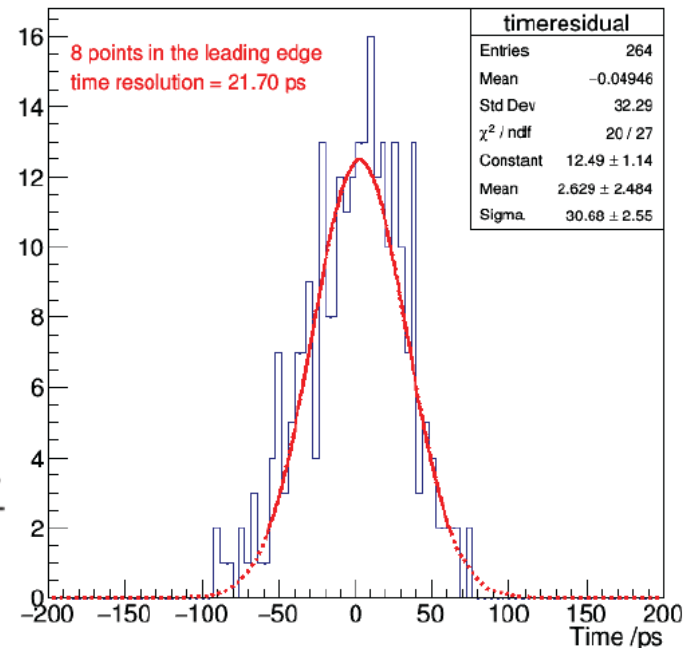
$$\sigma_{MRPC} = \frac{\sigma(\Delta t)}{\sqrt{2}}$$

- SCA+ADC **waveform** sampling
- Train with simulation data, test with **experiment** data

- Plot

$$Time = \frac{t_{est1l} + t_{est1r}}{2} - \frac{t_{est2l} + t_{est2r}}{2}$$

- The time resolution can reach 20 ps





Conclusions

- ✓ Time of flight system (TOF) based on MRPC technology is widely used and played an important role in modern high energy nuclear physics experiments.
- ✓ With the increase of accelerator energy and luminosity, many experiments have increasingly demand on the TOF for particle identification to have high resolution TOF under high data rate environment.
- ✓ New technology such as **New material** (low resistive glass), **New electronics** (switched capacitor array (SCA) and precision TDC) will be used in TOF system. New analysis method such as **deep learning technology** will play an very important role!



Thanks for your attention!